



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C220JB8NNND
- Description : CAP, 22pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

		<u>CL</u>	<u>10</u>	<u>C</u>	<u>220</u>	<u>J</u>	<u>B</u>	<u>8</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>D</u>	
		1	2	3	4	5	6	1	8	9	10	1	
① Series	Samsung	Multi-la	ayer C	eram	ic Cap	acito	or						
② Size	0603	(inch co	ode)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
③ Dielectric	C0G					(8)	Inne	r ele	ctroc	le		Ni	
<ul><li>④ Capacitance</li></ul>	22	рF				0	Term					Cu	
<b>⑤</b> Capacitance	±5	%					Plati	ng				Sn 100%	(Pb Free)
tolerance						9	Prod	luct				Normal	
Rated Voltage	50	V				10	Spec	cial				Reserved for	future use
⑦ Thickness	0.8	± 0.1	mm			1	Pack	agir	ng			Cardboard T	ype, 13" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1M±10% 0.5~5Vrms					
Q	840 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 $^\circ\!\!\!\mathrm{C}$ to 125 $^\circ\!\!\!\mathrm{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\!\!\mathrm{C}$ )						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5°C, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ <sub>p</sub> F whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 173.33 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger	Max. operating temperature					
	Q : 330 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
<b>Cycling</b> within $\pm 2.5\%$ or $\pm 0.25_{pF}$ whichever is larger		Min. operating temperature $\rightarrow$ 25 $^\circ$ C					
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C					
		5 cycle test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.